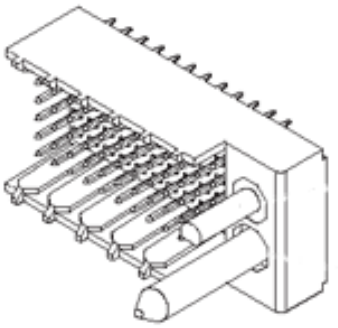
This document was generated on 05/14/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0739445000
Status: Active
Overview: hdm
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 144 Circuits



Series image - Reference only

Documents:
Drawing (PDF)
RoHS Certificate of Compliance (PDF)
Product Specification PS-73670-9999 (PDF)

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73944
Application	Backplane
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.118 In
PC Tail Length (mm)	3.00 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Polarized to PCB	No

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Not Reviewed
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
73944Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | **FAQ**
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.
Global

Description	Product #
HDM® Backplane Insertion Signal Contact Tool	0621001400
Extraction Tool	0621001000

Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

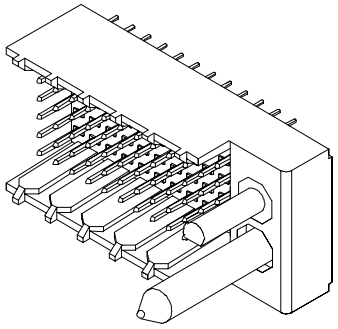
Reference - Drawing Numbers

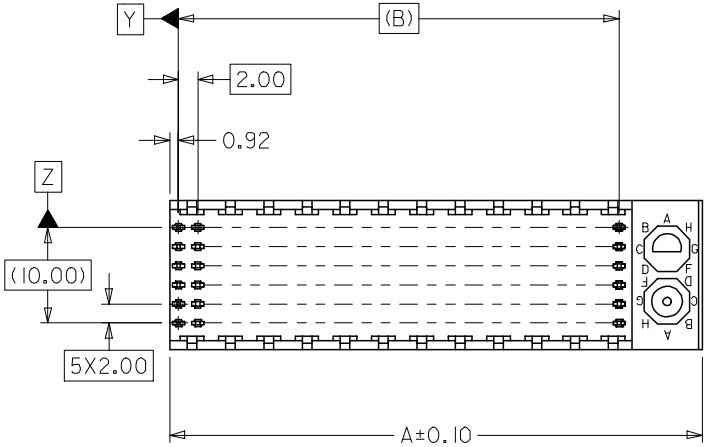
Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

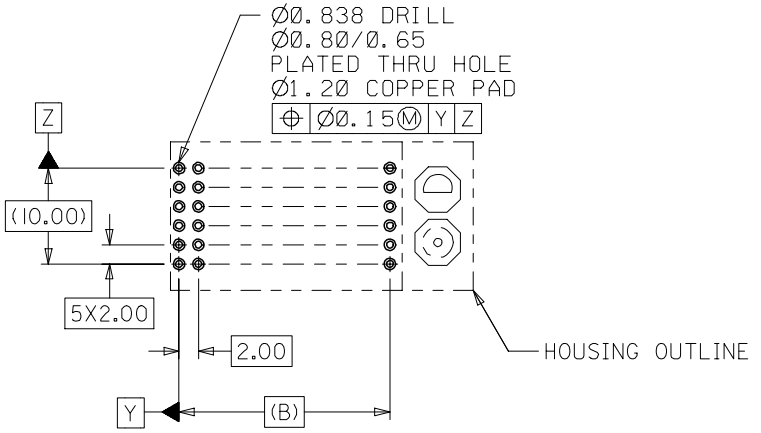
HDM and High Density Metric are trademarks of Amphenol Corporation

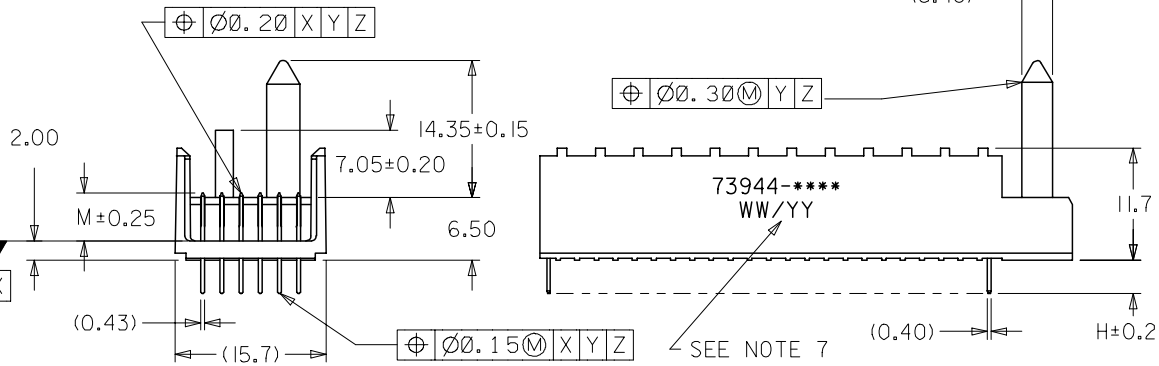
NOTES:

1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK,
   TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
   2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
   NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. SEE SHEET 2 FOR SPECIFIC MATERIAL NUMBERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.









PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

2	A
1	G
SHT	REV

MODIFY FINISH NOTE
EC NO: UCP2007-2259 2007/03/13
DRWN:MSIBARRA 2007/03/21
CH'KD:BBARKER
APPR:SMILLER 2007/03/22
DESCRIPTION
G
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.05	± ---
1 PLACE	± 0.10	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY	JBINGHAM	DATE 1998/01/14
CHECKED BY	SREED	DATE 1998/01/14
APPROVED BY	CBIXLER	DATE 1998/01/14

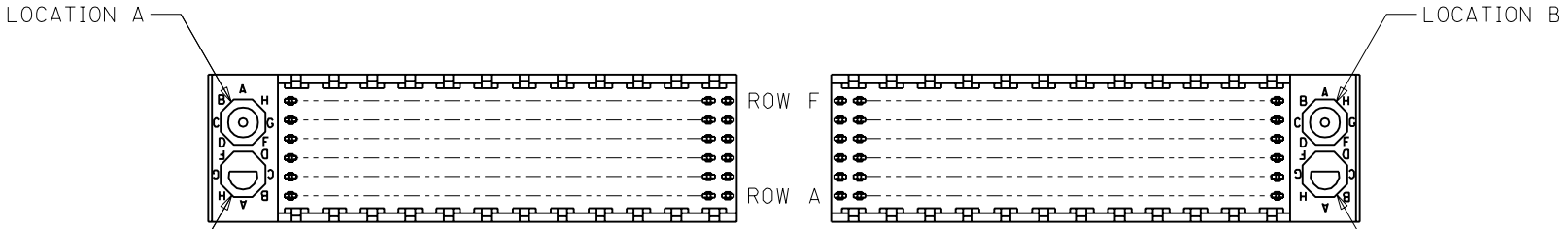
TITLE: SALES ASSY HDM BACKPLANE POLAR/GUIDE OPTION SOLDER TAIL VERSION

MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-73944-001
SHEET NO.: 1 OF 2

SIZE B

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



REF. MATERIAL NUMBER 73944-1009
GUIDE PIN IS IN LOCATION A
POLARIZING KEY IS IN LOCATION B, POSITION E

REF. MATERIAL NUMBER 73944-1008
GUIDE PIN IS IN LOCATION B
POLARIZING KEY IS IN LOCATION A, POSITION E

MATERIAL NUMBER ASSIGNMENT

73944- * * * *

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	31.60	22.00	2.00
1	144	55.60	46.00	2.00
2	72	31.60	22.00	2.50
3	144	55.60	46.00	2.50
4	72	31.60	22.00	3.00
5	144	55.60	46.00	3.00
6	72	31.60	22.00	3.50
7	144	55.60	46.00	3.50

NUMBER	DIM "M"
0	5.00
1	5.50
2	6.00

NUMBER	GUIDE POST LOCATION	POLAR KEY POSITION
00	B	A
01	A	
02	B	B
03	A	
04	B	C
05	A	
06	B	D
07	A	
08	B	E
09	A	
10	B	F
11	A	
12	B	G
13	A	
14	B	H
15	A	
16	B	N/A
17	A	
18	N/A	

SEE SHEET 1
EC NO. U81577 98/02/03
DRWN: BINGHAM 98/02/03
CH'K: REED 98/02/03
APPR: BIXLER 98/02/03
DESCRIPTION
A
REV

QUALITY SYMBOLS
MAJOR ▼ = 0
CRITICAL (C) = 0

GENERAL TOLERANCES: (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0.	±.
3 PLACES	±0.	±.
2 PLACES	±0.N/A	±.
1 PLACE	±0.N/A	±.
ANGULAR: ± 1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SCALE 2 : 1
DESIGN UNITS ☒mm ☐INCH
THIRD ANGLE PROJECTION
DIMENSIONS: ☐ mm/INCH ☐ INCH/mm ☒ mm ONLY
SHT REV
REVISE ON CAD ONLY

DRAWN BY & DATE: JBINGHAM 98/01/14
CHECKED BY & DATE: SREED 98/01/14
APPROVED BY & DATE: CBIXLER 98/01/14

TITLE: SALES ASSY, HDM BACKPLANE POLAR/GUIDE OPTION SOLDER TAIL VERSION

molex MOLEX INCORPORATED

CAD FILENAME: S73944X2.DGN
MATERIAL NO.: SEE CHART
DRAWING NO.: SD-73944-001
SHEET NO.: 2
SIZE: B

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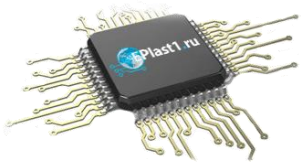
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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